### Details for "UC2834DWG4"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
UC2834DWG4	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DW   16	10.3x7.5x2.45	479

\*Total Device Mass

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The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

#### **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

# **Component Information**

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000031	0.007395	74	0.000006	0
Precious Metals	Gold	7440-57-5	0.419148	99.992605	999926	0.087499	875
Sub-Total			0.419179	100	1000000	0.087505	875
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.022686	2.000012	20000	0.004736	47
Precious Metals	Silver	7440-22-4	0.782662	68.999985	690000	0.163384	1634
Thermoplastics	Epoxy	85954-11-6	0.328945	29.000003	290000	0.068669	687
Sub-Total			1.134293	100	1000000	0.236788	2368
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	136.360887	97.532999	975330	28.465869	284659
Copper and Its Alloys	Iron	7439-89-6	3.239398	2.317	23170	0.676237	6762
Copper and Its Alloys	Phosphorus	7723-14-0	0.034953	0.025	250	0.007297	73
Zinc and Its Alloys	Zinc	7440-66-6	0.174763	0.125	1250	0.036482	365
Sub-Total			139.810001	100	1000000	29.185885	291859
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.702648	95.12	951200	0.355434	3554
Precious Metals	Gold	7440-57-5	0.013962	0.78	7800	0.002915	29
Precious Metals	Palladium	7440-05-3	0.07339	4.1	41000	0.01532	153
Sub-Total			1.79	100	1000000	0.37367	3737
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	291.164198	87.7	877000	60.781667	607817
Other Plastics and Rubber	Carbon Black	1333-86-4	0.996001	0.3	3000	0.207919	2079
Thermoplastics	Epoxy	85954-11-6	39.840027	12	120000	8.316762	83168
Sub-Total			332.000226	100	1000000	69.306348	693063
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.879229	100	1000000	0.809804	8098
Sub-Total			3.879229	100	1000000	0.809804	8098
Total			479.032928	1	1	100	1000000

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

#### Product Content Methodology

# For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

To certifies that the material content information provided by Ti is representative and accurate to the best of their knowledge based on material information provided by Its suppliers and their combination into finished IC packaged products. Ti semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

# Important Information/Disclaimer

The bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo

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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products are "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.